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"[Embedded - Microcontrollers](#)" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "[Embedded - Microcontrollers](#)"

Details

Product Status	Obsolete
Core Processor	R8C
Core Size	16-Bit
Speed	20MHz
Connectivity	CANbus, I ² C, IEBus, LINbus, SIO, SSU, UART/USART
Peripherals	POR, PWM, Voltage Detect, WDT
Number of I/O	43
Program Memory Size	128KB (128K x 8)
Program Memory Type	FLASH
EEPROM Size	4K x 8
RAM Size	10K x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	48-LQFP
Supplier Device Package	48-LQFP (7x7)
Purchase URL	https://www.e-xfl.com/product-detail/renesas-electronics-america/r5f2134cwjfp-u0

Table 1.6 Specifications for R8C/34Y Group (2)

Item	Function	Specification
Serial Interface	UART0	1 channel Clock synchronous serial I/O, UART
	UART2	1 channel Clock synchronous serial I/O, UART, I ² C mode (I ² C-bus), IE mode (IEBus), multiprocessor communication function
Synchronous Serial Communication Unit (SSU)		1 channel
LIN Module		Hardware LIN: 1 (timer RA, UART0)
A/D Converter		10-bit resolution × 12 channels, includes sample and hold function, with sweep mode
Flash Memory		• Programming and erasure voltage: VCC = 2.7 to 5.5 V • Programming and erasure endurance: 10,000 times (data flash) 1,000 times (program ROM) • Program security: ROM code protect, ID code check • Debug functions: On-chip debug, on-board flash rewrite function • Background operation (BGO) function (data flash)
Operating Frequency/Supply Voltage		f(XIN) = 20 MHz (VCC = 2.7 to 5.5 V)
Current Consumption		Typ. 7 mA (VCC = 5.0 V, f(XIN) = 20 MHz)
Operating Ambient Temperature		-40 to 85°C (J version) -40 to 125°C (K version) ⁽¹⁾
Package		48-pin LQFP Package code: PLQP0048KB-A (previous code: 48P6Q-A)

Note:

1. Specify the K version if K version functions are to be used.

Table 1.13 Pin Name Information by Pin Number (1)

Pin Number	Control Pin	Port	I/O Pin Functions for Peripheral Modules					
			Interrupt	Timer	Serial Interface	SSU	CAN Module (2)	A/D Converter Voltage Detection Circuit
1		P3_5			(CLK2) ⁽¹⁾	SSCK		
2		P3_3	$\overline{\text{INT3}}$		$\overline{\text{CTS2/RTS2}}$	(SSI) ⁽¹⁾ / $\overline{\text{SCS}}$		
3		P3_4			(TXD2)/(SDA2)/ (RXD2)/(SCL2) ⁽¹⁾	SSI/ $\overline{\text{SCS}}$ ⁽¹⁾		
4	MODE							
5		P4_3						
6		P4_4						
7	$\overline{\text{RESET}}$							
8	XOUT	P4_7						
9	VSS/AVSS							
10	XIN	P4_6						
11	VCC/AVCC							
12		P2_7		TRDIOD1				
13		P2_6		TRDIOC1				
14		P2_5		TRDIOB1				
15		P2_4		TRDIOA1				
16		P2_3		TRDIOD0				
17		P2_2		TRDIOC0				
18		P2_1		TRDIOB0				
19		P2_0		TRDIOA0/ TRDCLK				
20		P1_7	$\overline{\text{INT1}}$	(TRAIO) ⁽¹⁾				
21		P1_6			CLK0			
22		P1_5	$\overline{\text{INT1}}$ ⁽¹⁾	(TRAIO) ⁽¹⁾	RXD0			
23		P1_4		TRCCLK	TXD0			
24		P1_3	$\overline{\text{KI3}}$	TRBO				AN11
25		P4_5	$\overline{\text{INT0}}$					$\overline{\text{ADTRG}}$
26		P6_6	$\overline{\text{INT2}}$	TRCIOC	(TXD2)/(SDA2) ⁽¹⁾			

Notes:

1. This can be assigned to the pin in parentheses by a program.
2. Only for the R8C/34W Group and R8C/34X Group.

1.5 Pin Functions

Tables 1.15 and 1.16 list Pin Functions.

Table 1.15 Pin Functions (1)

Item	Pin Name	I/O Type	Description
Power supply input	VCC, VSS	–	Apply 2.7 V to 5.5 V to the VCC pin. Apply 0 V to the VSS pin.
Analog power supply input	AVCC, AVSS	–	Power supply for the A/D converter. Connect a capacitor between AVCC and AVSS.
Reset input	$\overline{\text{RESET}}$	I	Input “L” on this pin resets the MCU.
MODE	MODE	I	Connect this pin to VCC via a resistor.
XIN clock input	XIN	I	These pins are provided for XIN clock generation circuit I/O. Connect a ceramic resonator or a crystal oscillator between the XIN and XOUT pins ⁽¹⁾ . To use an external clock, input it to the XOUT pin and leave the XIN pin open.
XIN clock output	XOUT	I/O	
$\overline{\text{INT}}$ interrupt input	$\overline{\text{INT0}}$ to $\overline{\text{INT4}}$	I	$\overline{\text{INT}}$ interrupt input pins.
Key input interrupt	$\overline{\text{KI0}}$ to $\overline{\text{KI3}}$	I	Key input interrupt input pins
Timer RA	TRAIO	I/O	Timer RA I/O pin
	TRA0	O	Timer RA output pin
Timer RB	TRBO	O	Timer RB output pin
Timer RC	TRCCLK	I	External clock input pin
	TRCTR $\overline{\text{G}}$	I	External trigger input pin
	TRCIOA, TRCIOB, TRCIOC, TRCIOD	I/O	Timer RC I/O pins
Timer RD	TRDIOA0, TRDIOA1, TRDIOB0, TRDIOB1, TRDIOC0, TRDIOC1, TRDIOD0, TRDIOD1	I/O	Timer RD I/O pins
	TRDCLK	I	External clock input pin
Timer RE	TREO	O	Divided clock output pin
Serial interface	CLK0, CLK2	I/O	Transfer clock I/O pins
	RXD0, RXD2	I	Serial data input pins
	TXD0, TXD2	O	Serial data output pins
	$\overline{\text{CTS2}}$	I	Transmission control input pin
	$\overline{\text{RTS2}}$	O	Reception control output pin
	SCL2	I/O	I ² C mode clock I/O pin
	SDA2	I/O	I ² C mode data I/O pin
SSU	SSI	I/O	Data I/O pin
	$\overline{\text{SCS}}$	I/O	Chip-select signal I/O pin
	SSCK	I/O	Clock I/O pin
	SSO	I/O	Data I/O pin

I: Input O: Output I/O: Input and output

Note:

1. Refer to the oscillator manufacturer for oscillation characteristics.

2.1 Data Registers (R0, R1, R2, and R3)

R0 is a 16-bit register for transfer, arithmetic, and logic operations. The same applies to R1 to R3. R0 can be split into high-order bits (R0H) and low-order bits (R0L) to be used separately as 8-bit data registers. R1H and R1L are analogous to R0H and R0L. R2 can be combined with R0 and used as a 32-bit data register (R2R0). R3R1 is analogous to R2R0.

2.2 Address Registers (A0 and A1)

A0 is a 16-bit register for address register indirect addressing and address register relative addressing. It is also used for transfer, arithmetic, and logic operations. A1 is analogous to A0. A1 can be combined with A0 and as a 32-bit address register (A1A0).

2.3 Frame Base Register (FB)

FB is a 16-bit register for FB relative addressing.

2.4 Interrupt Table Register (INTB)

INTB is a 20-bit register that indicates the start address of an interrupt vector table.

2.5 Program Counter (PC)

PC is 20 bits wide and indicates the address of the next instruction to be executed.

2.6 User Stack Pointer (USP) and Interrupt Stack Pointer (ISP)

The stack pointers (SP), USP, and ISP, are each 16 bits wide. The U flag of FLG is used to switch between USP and ISP.

2.7 Static Base Register (SB)

SB is a 16-bit register for SB relative addressing.

2.8 Flag Register (FLG)

FLG is an 11-bit register indicating the CPU state.

2.8.1 Carry Flag (C)

The C flag retains carry, borrow, or shift-out bits that have been generated by the arithmetic and logic unit.

2.8.2 Debug Flag (D)

The D flag is for debugging only. Set it to 0.

2.8.3 Zero Flag (Z)

The Z flag is set to 1 when an arithmetic operation results in 0; otherwise to 0.

2.8.4 Sign Flag (S)

The S flag is set to 1 when an arithmetic operation results in a negative value; otherwise to 0.

2.8.5 Register Bank Select Flag (B)

Register bank 0 is selected when the B flag is 0. Register bank 1 is selected when this flag is set to 1.

2.8.6 Overflow Flag (O)

The O flag is set to 1 when an operation results in an overflow; otherwise to 0.

3.3 R8C/34Y Group

Figure 3.3 is a Memory Map of R8C/34Y Group. The R8C/34Y Group has a 1-Mbyte address space from addresses 00000h to FFFFFh. The internal ROM (program ROM) is allocated lower addresses, beginning with address 00FFFh. For example, a 48-Kbyte internal ROM area is allocated addresses 04000h to 0FFFFh.

The fixed interrupt vector table is allocated addresses 0FFDCh to 0FFFFh. The starting address of each interrupt routine is stored here.

The internal ROM (data flash) is allocated addresses 03000h to 03FFFh.

The internal RAM is allocated higher addresses, beginning with address 00400h. For example, a 4-Kbyte internal RAM area is allocated addresses 00400h to 013FFh. The internal RAM is used not only for data storage but also as a stack area when a subroutine is called or when an interrupt request is acknowledged.

Special function registers (SFRs) are allocated addresses 00000h to 002FFh and 02C00h to 02FFFh (the SFR areas for the DTC and other modules). Peripheral function control registers are allocated here. All unallocated spaces within the SFRs are reserved and cannot be accessed by users.

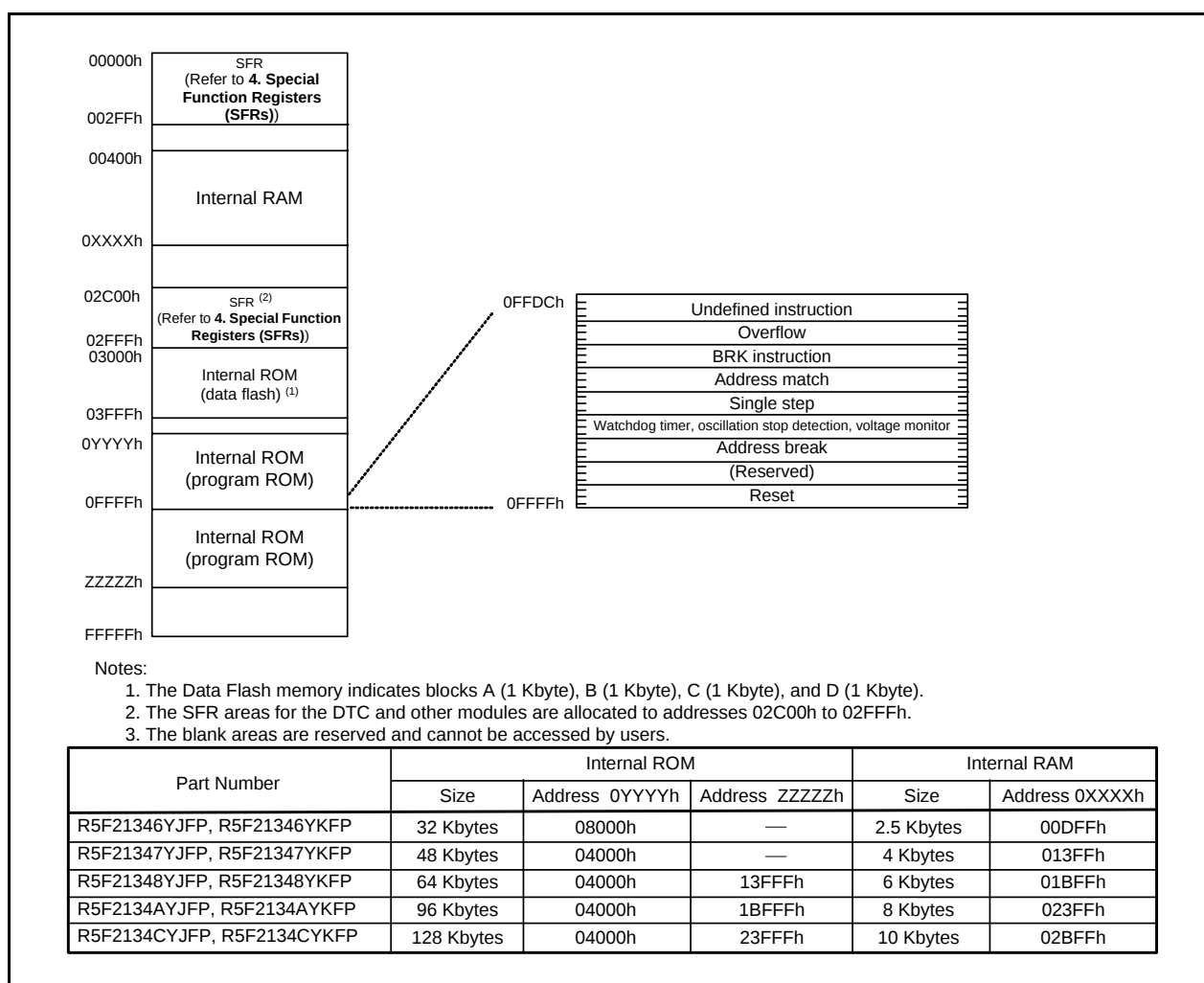


Figure 3.3 Memory Map of R8C/34Y Group

4. Special Function Registers (SFRs)

An SFR (special function register) is a control register for a peripheral function. Tables 4.1 to 4.17 list the special function registers. Table 4.18 lists the ID Code Areas and Option Function Select Area.

Table 4.1 SFR Information (1) (1)

Address	Register	Symbol	After reset
0000h			
0001h			
0002h			
0003h			
0004h	Processor Mode Register 0	PM0	00h
0005h	Processor Mode Register 1	PM1	00h
0006h	System Clock Control Register 0	CM0	00101000b
0007h	System Clock Control Register 1	CM1	00100000b
0008h	Module Standby Control Register	MSTCR	00h
0009h	System Clock Control Register 3	CM3	00h
000Ah	Protect Register	PRCR	00h
000Bh	Reset Source Determination Register	RSTFR	0XXXXXXb (2)
000Ch	Oscillation Stop Detection Register	OCD	00000100b
000Dh	Watchdog Timer Reset Register	WDTR	XXh
000Eh	Watchdog Timer Start Register	WDTS	XXh
000Fh	Watchdog Timer Control Register	WDTC	00111111b
0010h			
0011h			
0012h			
0013h			
0014h			
0015h	High-Speed On-Chip Oscillator Control Register 7	FRA7	When shipping
0016h			
0017h			
0018h			
0019h			
001Ah			
001Bh			
001Ch	Count Source Protection Mode Register	CSPR	00h 10000000b (3)
001Dh			
001Eh			
001Fh			
0020h			
0021h			
0022h			
0023h	High-Speed On-Chip Oscillator Control Register 0	FRA0	00h
0024h	High-Speed On-Chip Oscillator Control Register 1	FRA1	When shipping
0025h	High-Speed On-Chip Oscillator Control Register 2	FRA2	00h
0026h	On-Chip Reference Voltage Control Register	OCVREFCR	00h
0027h			
0028h			
0029h	High-Speed On-Chip Oscillator Control Register 4	FRA4	When Shipping
002Ah	High-Speed On-Chip Oscillator Control Register 5	FRA5	When Shipping
002Bh	High-Speed On-Chip Oscillator Control Register 6	FRA6	When Shipping
002Ch			
002Dh			
002Eh			
002Fh	High-Speed On-Chip Oscillator Control Register 3	FRA3	When shipping
0030h	Voltage Monitor Circuit Control Register	CMPA	00h
0031h	Voltage Monitor Circuit Edge Select Register	VCAC	00h
0032h			
0033h	Voltage Detect Register 1	VCA1	00001000b
0034h	Voltage Detect Register 2	VCA2	00h (4) 00100000b (5)
0035h			
0036h	Voltage Detection 1 Level Select Register	VD1LS	00000111b
0037h			
0038h	Voltage Monitor 0 Circuit Control Register	VW0C	1100X010b (4) 1100X011b (5)
0039h	Voltage Monitor 1 Circuit Control Register	VW1C	10001010b

X: Undefined

Notes:

1. The blank areas are reserved and cannot be accessed by users.
2. The CWR bit in the RSTFR register is set to 0 after power-on and voltage monitor 0 reset. Hardware reset, Software reset, or watchdog timer reset does not affect this bit.
3. The CSPROINI bit in the OFS register is set to 0.
4. The LVDAS bit in the OFS register is set to 1.
5. The LVDAS bit in the OFS register is set to 0.

Table 4.2 SFR Information (2) ⁽¹⁾

Address	Register	Symbol	After reset
003Ah	Voltage Monitor 2 Circuit Control Register	VW2C	10000010b
003Bh			
003Ch			
003Dh			
003Eh			
003Fh			
0040h			
0041h	Flash Memory Ready Interrupt Control Register	FMRDYIC	XXXXX000b
0042h			
0043h			
0044h			
0045h			
0046h	INT4 Interrupt Control Register	INT4IC	XX00X000b
0047h	Timer RC Interrupt Control Register	TRCIC	XXXXX000b
0048h	Timer RD0 Interrupt Control Register	TRD0IC	XXXXX000b
0049h	Timer RD1 Interrupt Control Register	TRD1IC	XXXXX000b
004Ah	Timer RE Interrupt Control Register	TREIC	XXXXX000b
004Bh	UART2 Transmit Interrupt Control Register	S2TIC	XXXXX000b
004Ch	UART2 Receive Interrupt Control Register	S2RIC	XXXXX000b
004Dh	Key Input Interrupt Control Register	KUPIC	XXXXX000b
004Eh	A/D Conversion Interrupt Control Register	ADIC	XXXXX000b
004Fh	SSU Interrupt Control Register	SSUIC	XXXXX000b
0050h			
0051h	UART0 Transmit Interrupt Control Register	S0TIC	XXXXX000b
0052h	UART0 Receive Interrupt Control Register	S0RIC	XXXXX000b
0053h			
0054h			
0055h	INT2 Interrupt Control Register	INT2IC	XX00X000b
0056h	Timer RA Interrupt Control Register	TRAIC	XXXXX000b
0057h			
0058h	Timer RB Interrupt Control Register	TRBIC	XXXXX000b
0059h	INT1 Interrupt Control Register	INT1IC	XX00X000b
005Ah	INT3 Interrupt Control Register	INT3IC	XX00X000b
005Bh			
005Ch			
005Dh	INT0 Interrupt Control Register	INT0IC	XX00X000b
005Eh	UART2 Bus Collision Detection Interrupt Control Register	U2BCNIC	XXXXX000b
005Fh			
0060h			
0061h			
0062h			
0063h			
0064h			
0065h			
0066h			
0067h			
0068h			
0069h			
006Ah			
006Bh			
006Ch	CAN0 Reception Complete Interrupt Control Register	C0RIC	XXXXX000b
006Dh	CAN0 Transmission Complete Interrupt Control Register	C0TIC	XXXXX000b
006Eh	CAN0 Receive FIFO Interrupt Control Register	C0FRIC	XXXXX000b
006Fh	CAN0 Transmit FIFO Interrupt Control Register	C0FTIC	XXXXX000b
0070h	CAN0 Error Interrupt Control Register	C0EIC	XXXXX000b
0071h	CAN0 Wake-up Interrupt Control Register	C0WIC	XXXXX000b
0072h	Voltage Monitor 1 Interrupt Control Register	VCMP1IC	XXXXX000b
0073h	Voltage Monitor 2 Interrupt Control Register	VCMP2IC	XXXXX000b
0074h			
0075h			
0076h			
0077h			
0078h			
0079h			
007Ah			
007Bh			
007Ch			
007Dh			
007Eh			
007Fh			

X: Undefined

Note:

1. The blank areas are reserved and cannot be accessed by users.

Table 4.4 SFR Information (4) (1)

Address	Register	Symbol	After reset
00C0h	A/D Register 0	AD0	XXh
00C1h			000000XXb
00C2h	A/D Register 1	AD1	XXh
00C3h			000000XXb
00C4h	A/D Register 2	AD2	XXh
00C5h			000000XXb
00C6h	A/D Register 3	AD3	XXh
00C7h			000000XXb
00C8h	A/D Register 4	AD4	XXh
00C9h			000000XXb
00CAh	A/D Register 5	AD5	XXh
00CBh			000000XXb
00CCh	A/D Register 6	AD6	XXh
00CDh			000000XXb
00CEh	A/D Register 7	AD7	XXh
00CFh			000000XXb
00D0h			
00D1h			
00D2h			
00D3h			
00D4h	A/D Mode Register	ADMOD	00h
00D5h	A/D Input Select Register	ADINSEL	11000000b
00D6h	A/D Control Register 0	ADCON0	00h
00D7h	A/D Control Register 1	ADCON1	00h
00D8h			
00D9h			
00DAh			
00DBh			
00DCh			
00DDh			
00DEh			
00DFh			
00E0h	Port P0 Register	P0	XXh
00E1h	Port P1 Register	P1	XXh
00E2h	Port P0 Direction Register	PD0	00h
00E3h	Port P1 Direction Register	PD1	00h
00E4h	Port P2 Register	P2	XXh
00E5h	Port P3 Register	P3	XXh
00E6h	Port P2 Direction Register	PD2	00h
00E7h	Port P3 Direction Register	PD3	00h
00E8h	Port P4 Register	P4	XXh
00E9h			
00EAh	Port P4 Direction Register	PD4	00h
00EBh			
00ECh	Port P6 Register	P6	XXh
00EDh			
00EEh	Port P6 Direction Register	PD6	00h
00EFh			
00F0h			
00F1h			
00F2h			
00F3h			
00F4h			
00F5h			
00F6h			
00F7h			
00F8h			
00F9h			
00FAh			
00FBh			
00FCh			
00FDh			
00FEh			
00FFh			

X: Undefined

Note:

1. The blank areas are reserved and cannot be accessed by users.

Table 4.8 SFR Information (8) (1)

Address	Register	Symbol	After reset
01C0h	Address Match Interrupt Register 0	RMAD0	XXh
01C1h			XXh
01C2h			0000XXXXb
01C3h	Address Match Interrupt Enable Register 0	AIER0	00h
01C4h	Address Match Interrupt Register 1	RMAD1	XXh
01C5h			XXh
01C6h			0000XXXXb
01C7h	Address Match Interrupt Enable Register 1	AIER1	00h
01C8h			
01C9h			
01CAh			
01CBh			
01CCh			
01CDh			
01CEh			
01CFh			
01D0h			
01D1h			
01D2h			
01D3h			
01D4h			
01D5h			
01D6h			
01D7h			
01D8h			
01D9h			
01DAh			
01DBh			
01DCh			
01DDh			
01DEh			
01DFh			
01E0h	Pull-Up Control Register 0	PUR0	00h
01E1h	Pull-Up Control Register 1	PUR1	00h
01E2h			
01E3h			
01E4h			
01E5h			
01E6h			
01E7h			
01E8h			
01E9h			
01EAh			
01EBh			
01ECh			
01EDh			
01EEh			
01EFh			
01F0h			
01F1h			
01F2h			
01F3h			
01F4h			
01F5h	Input Threshold Control Register 0	VLT0	00h
01F6h	Input Threshold Control Register 1	VLT1	00h
01F7h			
01F8h			
01F9h			
01FAh	External Input Enable Register 0	INTEN	00h
01FBh	External Input Enable Register 1	INTEN1	00h
01FCh	INT Input Filter Select Register 0	INTF	00h
01FDh	INT Input Filter Select Register 1	INTF1	00h
01FEh	Key Input Enable Register 0	KIEN	00h
01FFh			

X: Undefined

Note:

1. The blank areas are reserved and cannot be accessed by users.

Table 4.10 SFR Information (10) ⁽¹⁾

Address	Register	Symbol	After reset
2C70h	DTC Control Data 6	DTCD6	XXh
2C71h			XXh
2C72h			XXh
2C73h			XXh
2C74h			XXh
2C75h			XXh
2C76h			XXh
2C77h			XXh
2C78h	DTC Control Data 7	DTCD7	XXh
2C79h			XXh
2C7Ah			XXh
2C7Bh			XXh
2C7Ch			XXh
2C7Dh			XXh
2C7Eh			XXh
2C7Fh			XXh
2C80h	DTC Control Data 8	DTCD8	XXh
2C81h			XXh
2C82h			XXh
2C83h			XXh
2C84h			XXh
2C85h			XXh
2C86h			XXh
2C87h			XXh
2C88h	DTC Control Data 9	DTCD9	XXh
2C89h			XXh
2C8Ah			XXh
2C8Bh			XXh
2C8Ch			XXh
2C8Dh			XXh
2C8Eh			XXh
2C8Fh			XXh
2C90h	DTC Control Data 10	DTCD10	XXh
2C91h			XXh
2C92h			XXh
2C93h			XXh
2C94h			XXh
2C95h			XXh
2C96h			XXh
2C97h			XXh
2C98h	DTC Control Data 11	DTCD11	XXh
2C99h			XXh
2C9Ah			XXh
2C9Bh			XXh
2C9Ch			XXh
2C9Dh			XXh
2C9Eh			XXh
2C9Fh			XXh
2CA0h	DTC Control Data 12	DTCD12	XXh
2CA1h			XXh
2CA2h			XXh
2CA3h			XXh
2CA4h			XXh
2CA5h			XXh
2CA6h			XXh
2CA7h			XXh
2CA8h	DTC Control Data 13	DTCD13	XXh
2CA9h			XXh
2CAAh			XXh
2CABh			XXh
2CACH			XXh
2CADh			XXh
2CAEh			XXh
2CAFh			XXh

X: Undefined

Note:

1. The blank areas are reserved and cannot be accessed by users.

Table 5.3 Recommended Operating Conditions (2)

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
$I_{IC(H)}$	High input injection current	P0 to P2, P3_0, P3_1, P3_3 to P3_5, P3_7, P4_3 to P4_5, P6 $V_I > V_{CC}$	–	–	2	mA
$I_{IC(L)}$	Low input injection current	P0 to P2, P3_0, P3_1, P3_3 to P3_5, P3_7, P4_3 to P4_5, P6 $V_I < V_{SS}$	–	–	–2	mA
$\Sigma I_{IC} $	Total injection current		–	–	8	mA

Note:

1. $V_{CC} = 4.5$ to 5.5 V at $T_{opr} = -40$ to 85°C (J version) / -40 to 125°C (K version), unless otherwise specified.

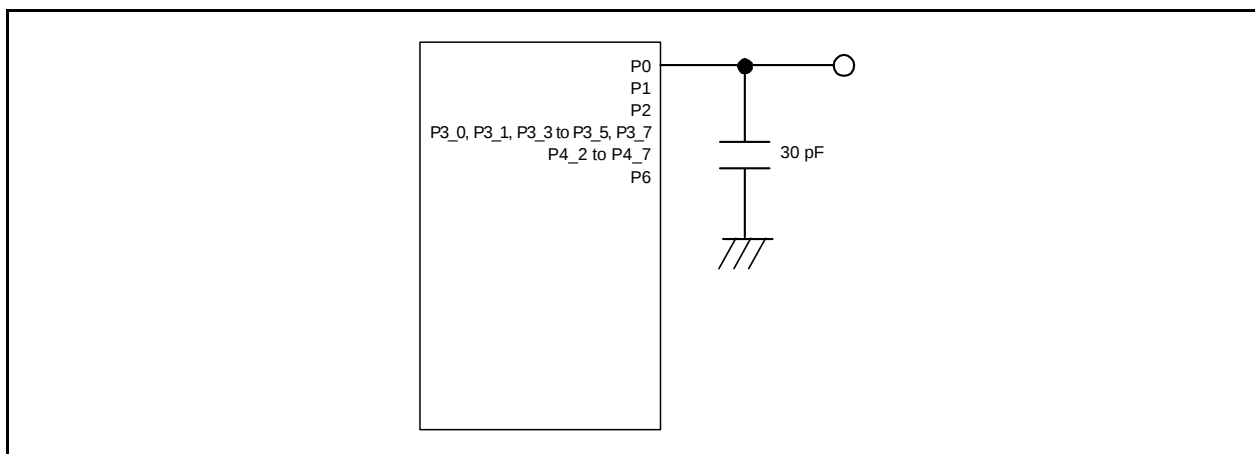
**Figure 5.1 Ports P0 to P2, P3_0, P3_1, P3_3 to P3_5, P3_7, P4_2 to P4_7, and P6 Timing Measurement Circuit**

Table 5.4 A/D Converter Characteristics

Symbol	Parameter		Conditions		Standard			Unit
					Min.	Typ.	Max.	
–	Resolution		Vref = AVCC		–	–	10	Bit
–	Absolute accuracy	10-bit mode	Vref = AVCC = 5.0 V	AN0 to AN7 input, AN8 to AN11 input	–	–	±3	LSB
			Vref = AVCC = 3.0 V	AN0 to AN7 input, AN8 to AN11 input	–	–	±5	LSB
		8-bit mode	Vref = AVCC = 5.0 V	AN0 to AN7 input, AN8 to AN11 input	–	–	±2	LSB
			Vref = AVCC = 3.0 V	AN0 to AN7 input, AN8 to AN11 input	–	–	±2	LSB
ϕAD	A/D conversion clock		4.0 ≤ Vref = AVCC = ≤ 5.5 ⁽²⁾		2	–	20	MHz
			2.7 ≤ Vref = AVCC = ≤ 5.5 ⁽²⁾		2	–	10	MHz
–	Tolerance level impedance				–	3	–	kΩ
Ivref	Vref current		VCC = 5.0 V, XIN = f1 = ϕAD = 20 MHz		–	45	–	μA
tCONV	Conversion time	10-bit mode	Vref = AVCC = 5.0 V, ϕAD = 20 MHz		2.2	–	–	μs
		8-bit mode	Vref = AVCC = 5.0 V, ϕAD = 20 MHz		2.2	–	–	μs
tSAMP	Sampling time		ϕAD = 20 MHz		0.8	–	–	μs
Vref	Reference voltage				2.7	–	AVCC	V
VIa	Analog input voltage ⁽³⁾				0	–	Vref	V
OCVREF	On-chip reference voltage		2 MHz ≤ ϕAD ≤ 4 MHz		1.14	1.34	1.54	V

Notes:

- $V_{CC}/AV_{CC} = V_{ref} = 2.7$ to 5.5 V , $V_{SS} = 0\text{ V}$ at $T_{opr} = -40$ to 85°C (J version) / -40 to 125°C (K version), unless otherwise specified.
- The A/D conversion result will be undefined in wait mode, stop mode, when the flash memory stops, and in low-consumption current mode. Do not perform A/D conversion in these states or transition to these states during A/D conversion.
- When the analog input voltage is over the reference voltage, the A/D conversion result will be 3FFh in 10-bit mode and FFh in 8-bit mode.

Table 5.6 Flash Memory (Data flash Block A to Block D) Electrical Characteristics

Symbol	Parameter	Conditions	Standard			Unit
			Min.	Typ.	Max.	
–	Program/erase endurance ⁽²⁾		10,000 ⁽³⁾	–	–	times
–	Byte program time (program/erase endurance ≤ 1,000 times)		–	160	950	μs
–	Byte program time (program/erase endurance > 1,000 times)		–	300	950	μs
–	Block erase time (program/erase endurance ≤ 1,000 times)		–	0.2	1	s
–	Block erase time (program/erase endurance > 1,000 times)		–	0.3	1	s
t _d (SR-SUS)	Time delay from suspend request until suspend		–	–	3+CPU clock × 3 cycles	ms
–	Interval from erase start/restart until following suspend request		0	–	–	μs
–	Time from suspend until erase restart		–	–	30+CPU clock × 1 cycle	μs
t _d (CMDRST-READY)	Time from when command is forcibly terminated until reading is enabled		–	–	30+CPU clock × 1 cycle	μs
–	Program, erase voltage		2.7	–	5.5	V
–	Read voltage		2.7	–	5.5	V
–	Program, erase temperature		–40	–	85 (J version) 125 (K version)	°C
–	Data hold time ⁽⁷⁾	Ambient temperature = 55 °C ⁽⁸⁾	20	–	–	year

Notes:

- V_{CC} = 2.7 to 5.5 V at T_{opr} = –40 to 85°C (J version) / –40 to 125°C (K version), unless otherwise specified.
- Definition of programming/erasure endurance
The programming and erasure endurance is defined on a per-block basis.
If the programming and erasure endurance is n (n = 100, 1,000, 10,000), each block can be erased n times. For example, if 1,024 1-byte writes are performed to different addresses in block A, a 1 Kbyte block, and then the block is erased, the programming/erasure endurance still stands at one.
However, the same address must not be programmed more than once per erase operation (overwriting prohibited).
- Endurance to guarantee all electrical characteristics after program and erase. (1 to Min. value can be guaranteed).
- In a system that executes multiple programming operations, the actual erasure count can be reduced by writing to sequential addresses in turn so that as much of the block as possible is used up before performing an erase operation. For example, when programming groups of 16 bytes, the effective number of rewrites can be minimized by programming up to 128 groups before erasing them all in one operation. In addition, averaging the erasure endurance between blocks A to D can further reduce the actual erasure endurance. It is also advisable to retain data on the erasure endurance of each block and limit the number of erase operations to a certain number.
- If an error occurs during block erase, attempt to execute the clear status register command, then execute the block erase command at least three times until the erase error does not occur.
- Customers desiring program/erase failure rate information should contact their Renesas technical support representative.
- The data hold time includes time that the power supply is off or the clock is not supplied.
- This data hold time includes 3,000 hours in T_a = 125°C and 7,000 hours in T_a = 85°C.

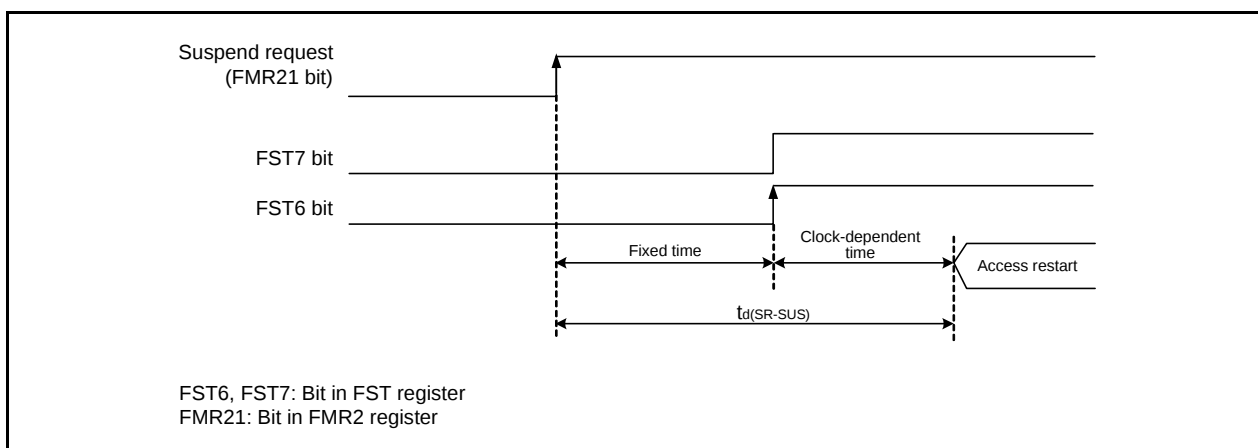
**Figure 5.2 Time delay until Suspend**

Table 5.7 Voltage Detection 0 Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V _{det0}	Voltage detection level	At the falling of V _{CC}	2.70	2.85	3.00	V
—	Voltage detection 0 circuit response time ⁽³⁾	At the falling of V _{CC} from 5 V to (V _{det0} – 0.1) V	—	6	150	μs
—	Voltage detection circuit self power consumption	VCA25 = 1, V _{CC} = 5.0 V	—	1.5	—	μA
t _{d(E-A)}	Wait time until voltage detection circuit operation starts ⁽²⁾		—	—	100	μs

Notes:

1. The measurement condition is V_{CC} = 2.7 V to 5.5 V and T_{opr} = –40 to 85°C (J version) / –40 to 125°C (K version).
2. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA25 bit in the VCA2 register to 0.
3. Time until the voltage monitor 0 reset is generated after the voltage passes V_{det0}.

Table 5.8 Voltage Detection 1 Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V _{det1}	Voltage detection level V _{det1_7} ⁽²⁾	At the falling of V _{CC}	3.05	3.25	3.45	V
	Voltage detection level V _{det1_8} ⁽²⁾	At the falling of V _{CC}	3.20	3.40	3.60	V
	Voltage detection level V _{det1_9} ⁽²⁾	At the falling of V _{CC}	3.35	3.55	3.75	V
	Voltage detection level V _{det1_A} ⁽²⁾	At the falling of V _{CC}	3.50	3.70	3.90	V
	Voltage detection level V _{det1_B} ⁽²⁾	At the falling of V _{CC}	3.65	3.85	4.05	V
	Voltage detection level V _{det1_C} ⁽²⁾	At the falling of V _{CC}	3.80	4.00	4.20	V
	Voltage detection level V _{det1_D} ⁽²⁾	At the falling of V _{CC}	3.95	4.15	4.35	V
	Voltage detection level V _{det1_E} ⁽²⁾	At the falling of V _{CC}	4.10	4.30	4.50	V
—	Hysteresis width at the rising of V _{CC} in voltage detection 1 circuit		—	0.1	—	V
—	Voltage detection 1 circuit response time ⁽³⁾	At the falling of V _{CC} from 5 V to (V _{det1_7} – 0.1) V	—	60	150	μs
—	Voltage detection circuit self power consumption	VCA26 = 1, V _{CC} = 5.0 V	—	1.7	—	μA
t _{d(E-A)}	Wait time until voltage detection circuit operation starts ⁽⁴⁾		—	—	100	μs

Notes:

1. The measurement condition is V_{CC} = 2.7 V to 5.5 V and T_{opr} = –40 to 85°C (J version) / –40 to 125°C (K version).
2. Select the voltage detection level with bits VD1S0 to VD1S3 in the VD1LS register.
3. Time until the voltage monitor 1 interrupt request is generated after the voltage passes V_{det1}.
4. Necessary time until the voltage detection circuit operates when setting to 1 again after setting the VCA26 bit in the VCA2 register to 0.

Table 5.9 Voltage Detection 2 Circuit Electrical Characteristics

Symbol	Parameter	Condition	Standard			Unit
			Min.	Typ.	Max.	
V _{det2}	Voltage detection level V _{det2}	At the falling of V _{CC}	3.80	4.00	4.20	V
—	Hysteresis width at the rising of V _{CC} in voltage detection 2 circuit		—	0.1	—	V
—	Voltage detection 2 circuit response time ⁽²⁾	At the falling of V _{CC} from 5 V to (V _{det2} – 0.1) V	—	20	150	μs
—	Voltage detection circuit self power consumption	VCA26 = 1, V _{CC} = 5.0 V	—	1.7	—	μA
t _{d(E-A)}	Wait time until voltage detection circuit operation starts ⁽³⁾		—	—	100	μs

Notes:

1. The measurement condition is V_{CC} = 2.7 V to 5.5 V and T_{opr} = –40 to 85°C (J version) / –40 to 125°C (K version).
2. Time until the voltage monitor 2 interrupt request is generated after the voltage passes V_{det2}.
3. Necessary time until the voltage detection circuit operates after setting to 1 again after setting the VCA27 bit in the VCA2 register to 0.

Table 5.14 Timing Requirements of SSU (1)

Symbol	Parameter		Conditions	Standard			Unit
				Min.	Typ.	Max.	
tsucyc	SSCK clock cycle time			4	–	–	tcyc (2)
tHI	SSCK clock "H" width			0.4	–	0.6	tsucyc
tLO	SSCK clock "L" width			0.4	–	0.6	tsucyc
trISE	SSCK clock rising time	Master		–	–	1	tcyc (2)
		Slave		–	–	1	μs
tFALL	SSCK clock falling time	Master		–	–	1	tcyc (2)
		Slave		–	–	1	μs
tsu	SSO, SSI data input setup time			100	–	–	ns
tH	SSO, SSI data input hold time			1	–	–	tcyc (2)
tLEAD	SCS setup time	Slave		1tcyc + 50	–	–	ns
tLAG	SCS hold time	Slave		1tcyc + 50	–	–	ns
tOD	SSO, SSI data output delay time			–	–	1	tcyc (2)
tSA	SSI slave access time		$2.7\text{ V} \leq V_{CC} \leq 5.5\text{ V}$	–	–	$1.5tcyc + 100$	ns
tOR	SSI slave out open time		$2.7\text{ V} \leq V_{CC} \leq 5.5\text{ V}$	–	–	$1.5tcyc + 100$	ns

Notes:

1. The measurement condition is $V_{CC} = 2.7$ to 5.5 V and $T_{opr} = -40$ to 85°C (J version) / -40 to 125°C (K version).
2. $1tcyc = 1/f_1(\text{s})$

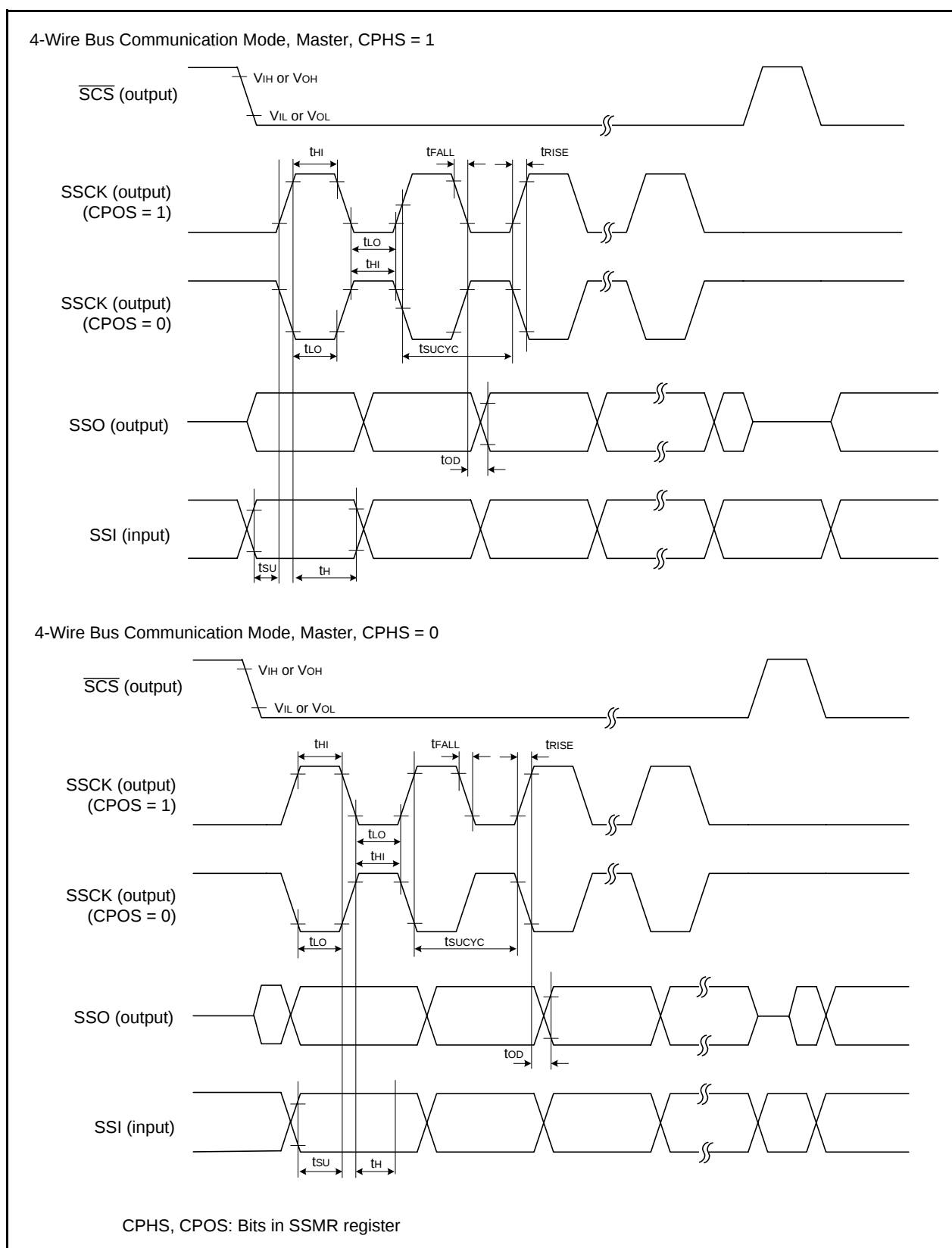


Figure 5.4 I/O Timing of SSU (Master)

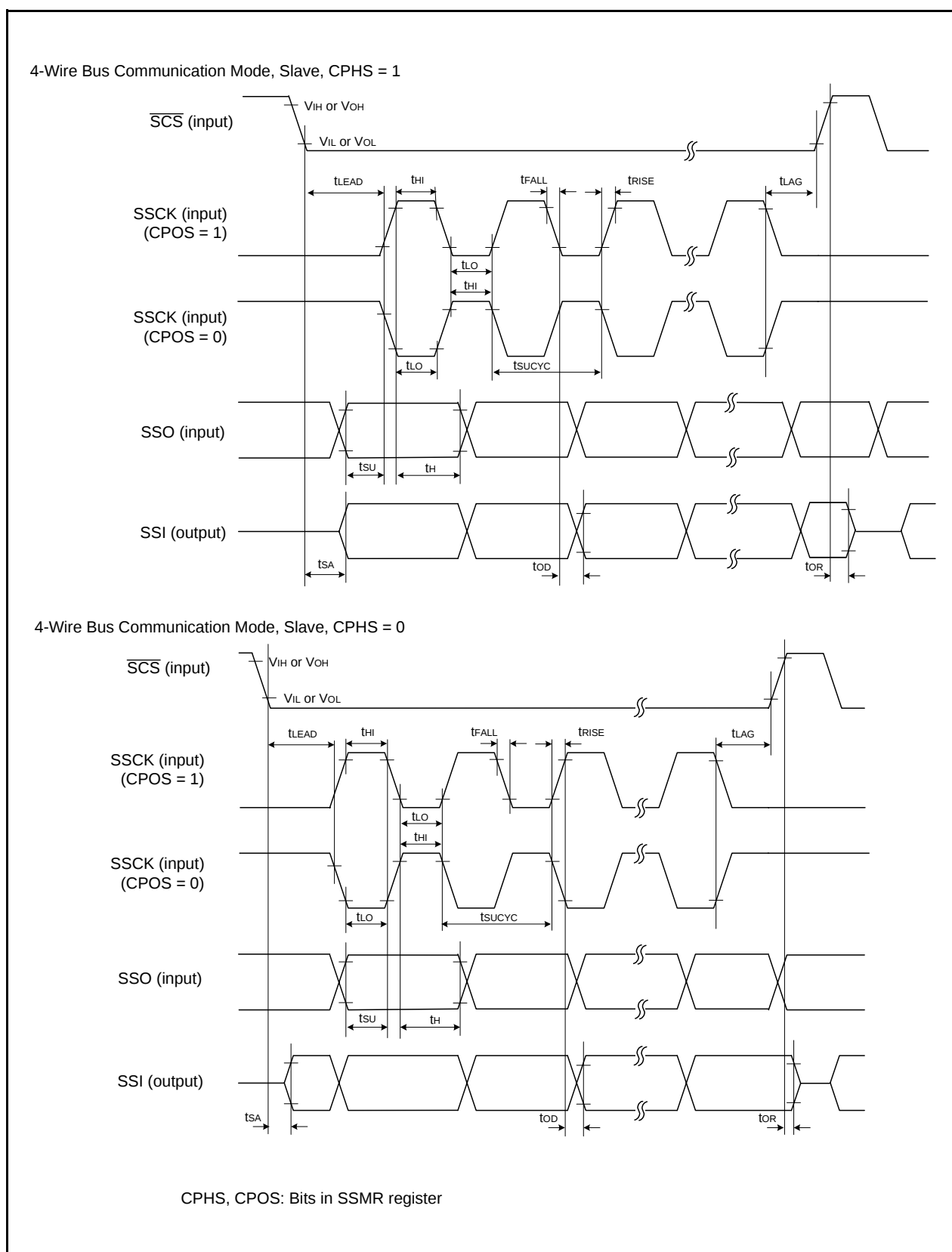


Figure 5.5 I/O Timing of SSU (Slave)

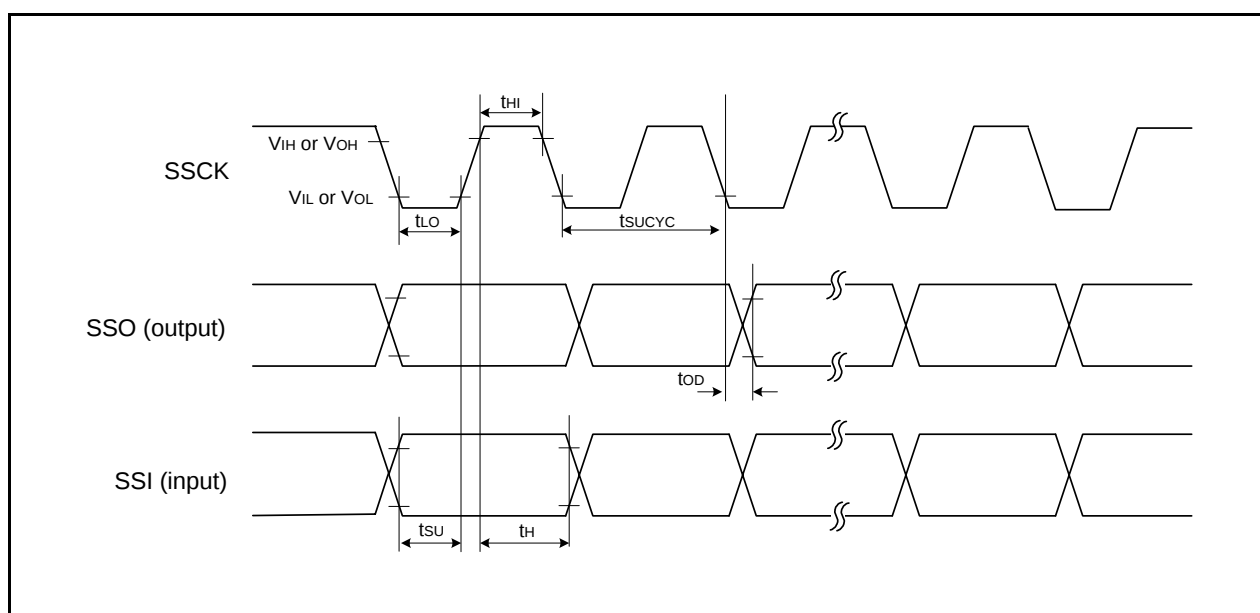


Figure 5.6 I/O Timing of SSU (Clock Synchronous Communication Mode)

Table 5.15 Electrical Characteristics (1) [$4.2\text{ V} \leq V_{CC} \leq 5.5\text{ V}$]

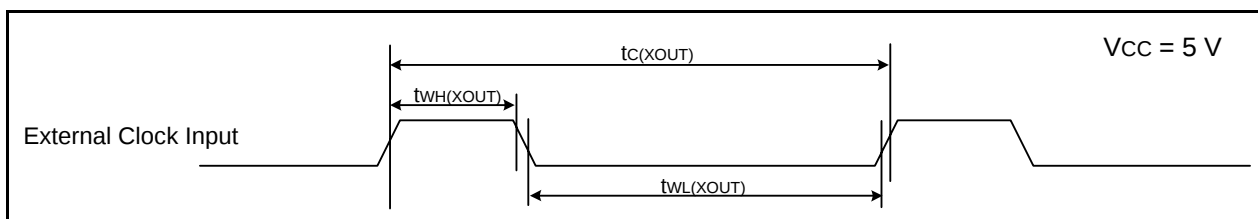
Symbol	Parameter		Condition	Standard			Unit
				Min.	Typ.	Max.	
V _{OH}	Output "H" voltage	Other than XOUT	I _{OH} = -5 mA	V _{CC} - 2.0	—	V _{CC}	V
			I _{OH} = -200 μ A	V _{CC} - 0.3	—	V _{CC}	V
		XOUT	I _{OH} = -200 μ A	1.0	—	V _{CC}	V
V _{OL}	Output "L" voltage	Other than XOUT	I _{OL} = 5 mA	—	—	2.0	V
			I _{OL} = 200 μ A	—	—	0.45	V
		XOUT	I _{OH} = -200 μ A	—	—	0.5	V
V _{T+} -V _{T-}	Hysteresis	INT0 to INT4, KI0 to KI3, TRAIO, TRBO, TRCIOA to TRCIOD, TRDIOA0 to TRDIOD0, TRDIOA1 to TRDIOD1, TRCCLK, TRDCLK, TRCTRG, ADTRG, RXD0, RXD2, CLK0, CLK2, SSI, SCL2, SDA2, SSO		0.1	1.2	—	V
		RESET		0.1	1.2	—	V
I _{IH}	Input "H" current		V _I = 5 V, V _{CC} = 5.0 V	—	—	1.0	μ A
I _{IL}	Input "L" current		V _I = 0 V, V _{CC} = 5.0 V	—	—	-1.0	μ A
R _{PULLUP}	Pull-up resistance		V _I = 0 V, V _{CC} = 5.0 V	25	50	100	k Ω
R _{FXIN}	Feedback resistance	XIN		—	0.3	—	M Ω
V _{RAM}	RAM hold voltage		During stop mode	2.0	—	—	V

Note:

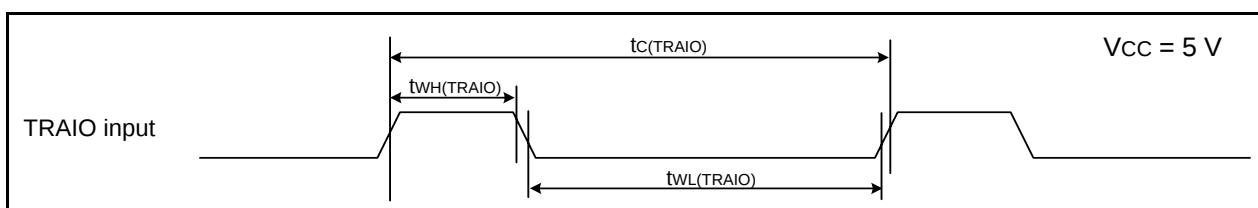
1. $4.2\text{ V} \leq V_{CC} \leq 5.5\text{ V}$ at T_{opr} = -40 to 85°C (J version) / -40 to 125°C (K version), f(XIN) = 20 MHz, unless otherwise specified.

Timing Requirements**(Unless Otherwise Specified: $V_{CC} = 5\text{ V}$, $V_{SS} = 0\text{ V}$ at $T_{opr} = -40^{\circ}\text{C}$ to 85°C (J ver)/ -40°C to 125°C (K ver))****Table 5.18 External clock input (XOUT)**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(XOUT)}$	XOUT input cycle time	50	–	ns
$t_{WH(XOUT)}$	XOUT input “H” width	24	–	ns
$t_{WL(XOUT)}$	XOUT input “L” width	24	–	ns

**Figure 5.7 External Clock Input Timing Diagram when $V_{CC} = 5\text{ V}$** **Table 5.19 TRAIO Input**

Symbol	Parameter	Standard		Unit
		Min.	Max.	
$t_{c(TRAIO)}$	TRAIO input cycle time	100	–	ns
$t_{WH(TRAIO)}$	TRAIO input “H” width	40	–	ns
$t_{WL(TRAIO)}$	TRAIO input “L” width	40	–	ns

**Figure 5.8 TRAIO Input Timing Diagram when $V_{CC} = 5\text{ V}$**